

Comments and Corrections

Corrections to “Simulation Methodologies for Acoustic Noise Induced by Multilayer Ceramic Capacitors of Power Distribution Network in Mobile Systems”

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In [1], reference [2] is missing. It should be added after citation “11” in Section I, paragraph 3: “To evaluate the MLCC caused PCB vibration during early design stage, it is preferable to develop a proper simulation methodology for the PCB dynamic characteristics. Many research works have concentrated on the board fatigue failure prediction [7] and improvement of finite element numerical methods [8]. The intrinsic board vibration properties is also investigated through modal analysis simulation [9], [10]. The forced PCB vibration subjected to MLCC vibration can also be analyzed through simulation with harmonic analysis [11]. However, the influence of MLCC location on the vibration amplitude is not considered and validated. In addition, the effect of board parameters to board vibration properties has not been clearly evaluated. Furthermore, there has been no demonstration to accommodate parameter variations in the modal analysis simulation.”

REFERENCES

- [1] Y. Sun, S. Wu, J. Zhang, C. Hwang, and Z. Yang, “Simulation methodologies for acoustic noise induce by multilayer ceramic capacitors of power distribution network in mobile systems,” *IEEE Trans. Electromagn. Compat.*, vol. 63, no. 2, pp. 589–597, Apr. 2021.
- [2] T. Lu, M. Ding, and K. Wu, “Simulation and characterization of singing capacitors in consumer electronics,” in *Proc. IEEE Int. Symp. Electromagn. Compat.*, Jul. 2019, pp. 522–526.

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